

Method of forming dielectric films, new precursors and their use in the semi-conductor manufacturing

5

Abstract

Method of deposition on a substrate, of a metal containing dielectric film comprising a compound of the formula (I):



10 wherein $0 \leq a < 1$, $0 < b \leq 3$, $0 \leq c \leq 1$, M^1 represents a metal selected from (Hf), (Zr) and (Ti); and M^2 represents a metal atom atoms, which comprises the following steps:

- A step a) of providing a substrate into a reaction chamber;

- A step (b) of vaporizing a M^1 metal containing precursor selected from:

15 Zr(MeCp)(NMe₂)₃, Zr(EtCp)(NMe₂)₃, ZrCp(NMe₂)₃, Zr(MeCp)(NEtMe)₃,
Zr(EtCp)(NEtMe)₃, ZrCp(NEtMe)₃, Zr(MeCp)(NEt₂)₃, Zr(EtCp)(NEt₂)₃,
ZrCp(NEt₂)₃, Zr(iPr₂Cp)(NMe₂)₃, Zr(tBu₂Cp)(NMe₂)₃, Hf(MeCp)(NMe₂)₃,
Hf(EtCp)(NMe₂)₃, HfCp(NMe₂)₃, Hf(MeCp)(NEtMe)₃, Hf(EtCp)(NEtMe)₃,
HfCp(NEtMe)₃, Hf(MeCp)(NEt₂)₃, Hf(EtCp)(NEt₂)₃, HfCp(NEt₂)₃,
20 Hf(iPr₂Cp)(NMe₂)₃, Hf(tBu₂Cp)(NMe₂)₃, to form a first gas phase metal source;

- A step c) of introducing the first gas phase metal source in the reaction chamber, in order to provoke their contact with said substrate, to generate the deposition of a metal containing dielectric film comprising a compound of the formula (I) as hereinbefore defined, on said substrate.

25

(no suitable figure)